

HSU227

Silicon Schottky Barrier Diode for High Speed Switching

REJ03G0612-0200
(Previous: ADE-208-779A)
Rev.2.00
Apr 28, 2005

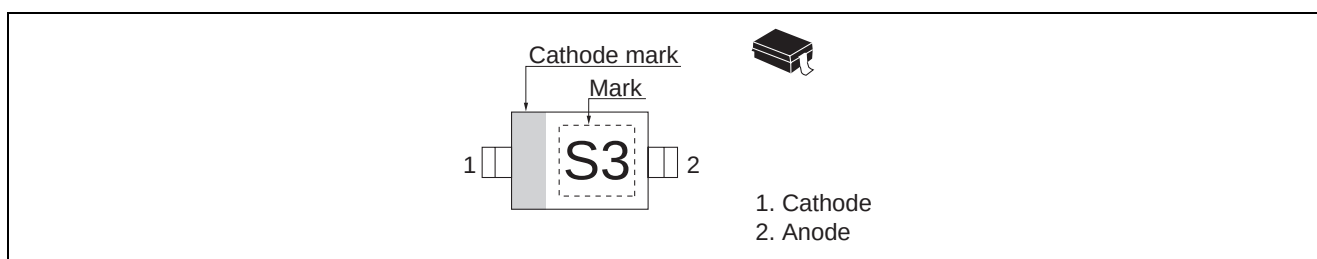
Features

- Low capacitance. (C = 3.0 pF max)
- Ultra small Resin Package (URP) is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Name	Package Code (Previous Code)
HSU227	S3	URP	PTSP0002ZA-A (URP)

Pin Arrangement



Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Repetitive peak reverse voltage	V_{RRM}	25	V
Average rectified current	I_O	50	mA
Non-Repetitive peak forward surge current	I_{FSM}^{*1}	200	mA
Junction temperature	T_j	125	°C
Storage temperature	T_{stg}	-55 to +125	°C

Note: 1. 10 ms sine wave 1 pulse.

Electrical Characteristics

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward voltage	V_F	—	0.29	0.35	V	$I_F = 1 \text{ mA}$
Reverse current	I_R	—	0.3	2.0	μA	$V_R = 20 \text{ V}$
Capacitance	C	—	2.45	3.00	pF	$V_R = 1 \text{ V}, f = 1 \text{ MHz}$

Main Characteristic

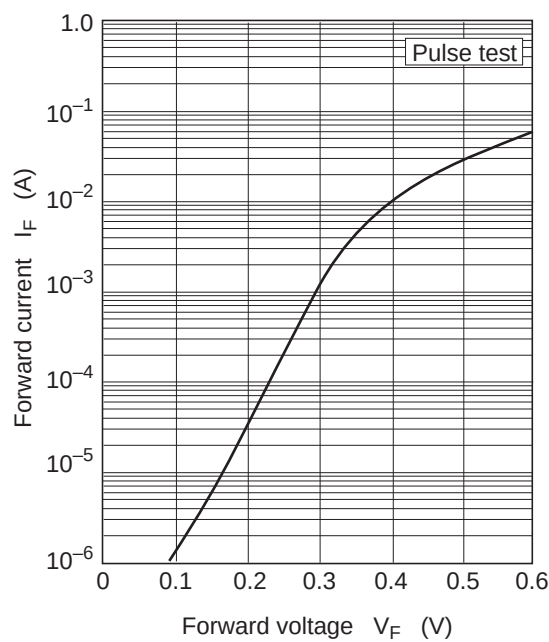


Fig.1 Forward current vs. Forward voltage

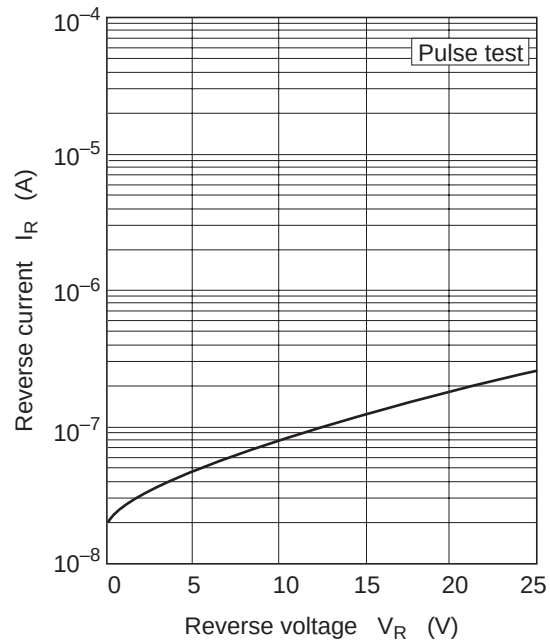


Fig.2 Reverse current vs. Reverse voltage

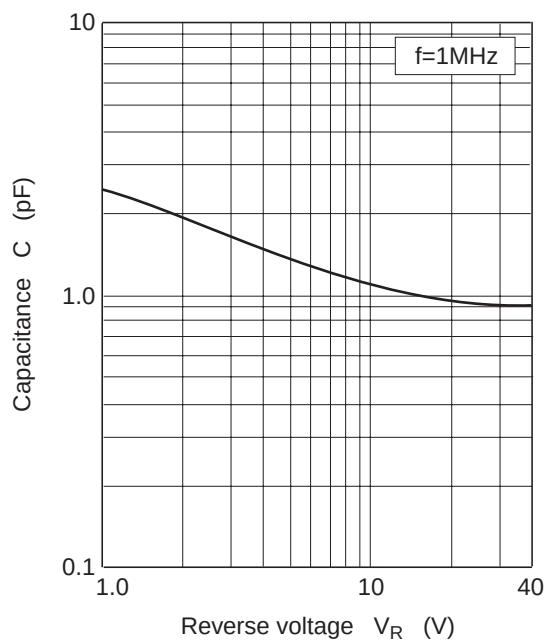
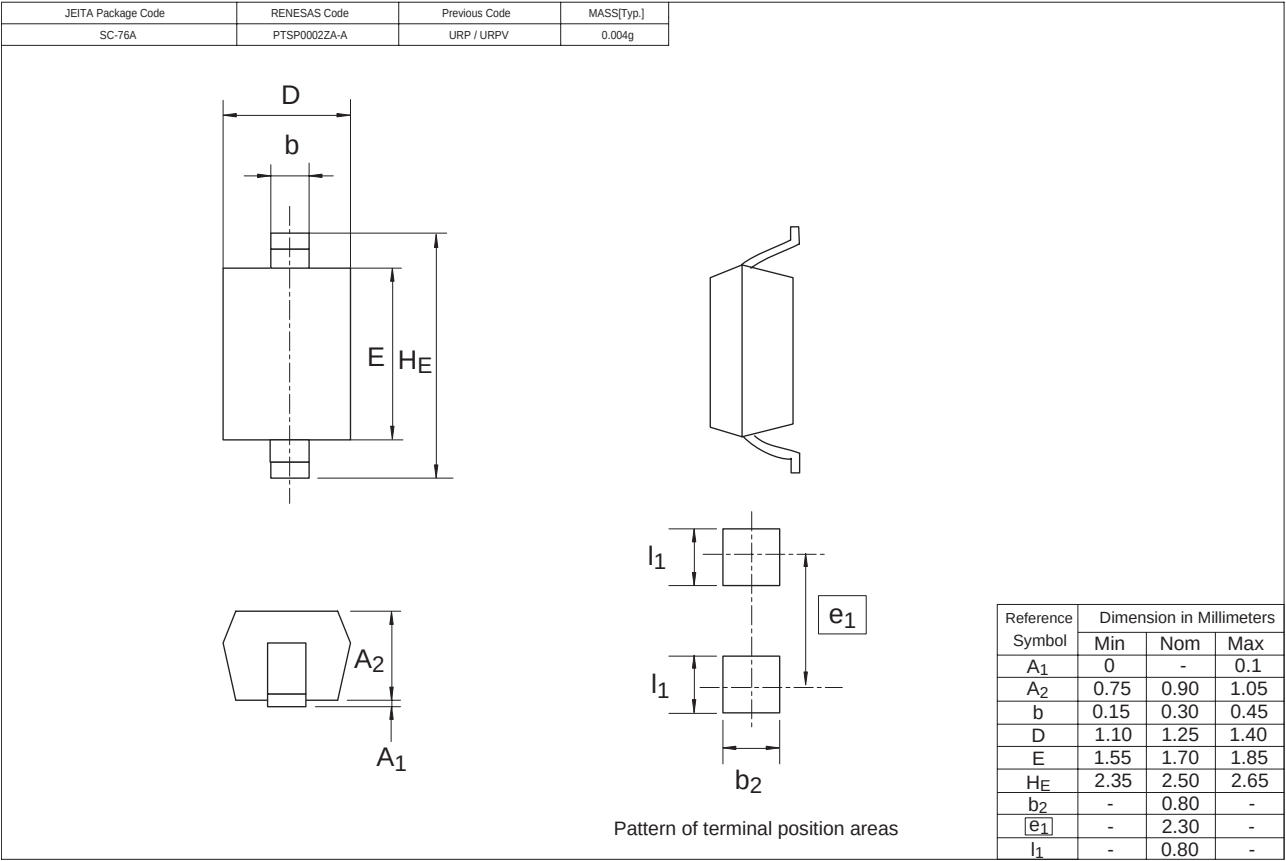


Fig.3 Capacitance vs. Reverse voltage

Package Dimensions



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